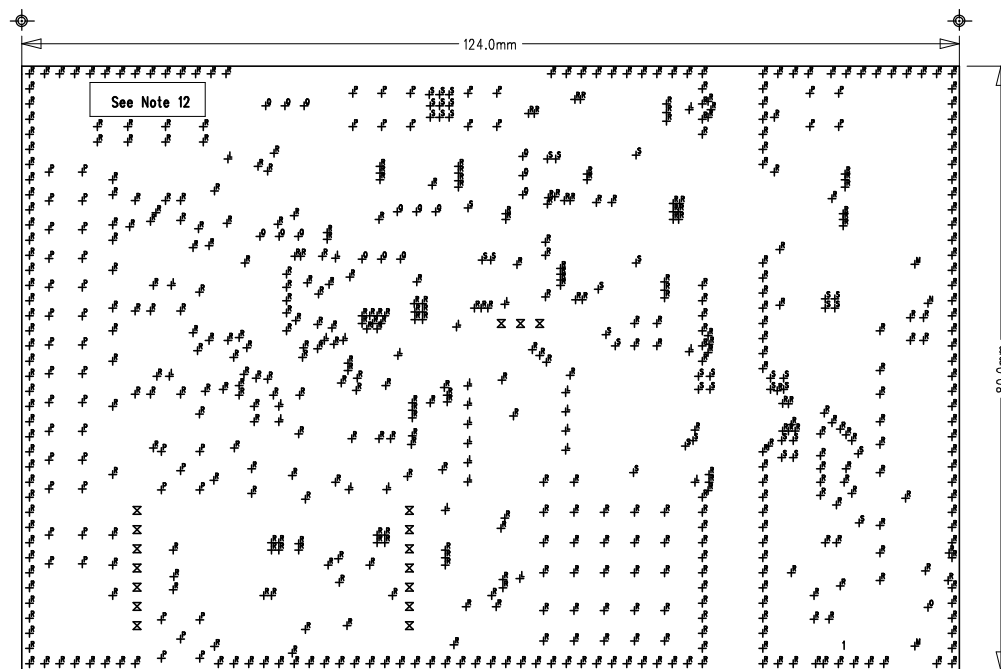


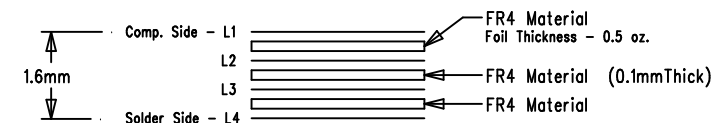
SIZE	QTY	SYM	PLATED	TOL
0.889	17	⊗	YES	+/-2.0
1.0414	28	+ ^L	YES	+/-2.0
3.1	2	+ ^M	NO	+/-0.0
1.1	1	+ ^N	NO	+/-0.0
0.7	1	+ ^O	NO	+/-0.0
1.524	52	+ ^P	YES	+/-0.0
0.9398	15	+ ^Q	YES	+/-0.0
0.25	535	+ ^R	YES	+/-0.0
0.6	40	+ ^S	YES	+/-0.0



EVAL-CN0292-SDZ (08-038798) (Rev. B) - Component Side View
Layer 1 - Component Side

Drill Template

- Material: Four layer, FR4 glass epoxy laminate, 0.062' +/-0.007' thick.
0.5oz. copper clad - external layers.
0.5oz. copper clad - internal layers.
See Diagram Below for Stack-up - Note critical 0.1mm thickness between L2 & L3
Finished Board to be RoHS & REACH Compliant.
- Plated thru holes and the conductive pattern electroplated with 0.001' min. thick copper. Terminal areas and plated thru holes to be ENIG plated.
Soldermask over bare copper.
- All Boards to be Electrically Tested prior to shipment
- Datum for (x,y) co-ordinate drill files at this hole.
- Processing tolerances:
 - Conductive pattern front to back registration within .005' total.
 - Minimum annular ring surrounding holes: 0.002'
 - Finished conductive pattern within .002' of true size.
- Warp and twist within .010 inch per inch
- Dimensions are for the finished part.
- Solder Mask: Liquid photo imangible solder mask over bare copper (smobc), colour green, both sides using the patterns provided. No mask is permitted on the terminal areas. Soldermask to etch registration within .005' total.
- Screening: Screen component outlines and nomenclature using indelible white ink on the primary and secondary sides (as required). Nomenclature shall be legible. Screen to etch registration within .020' total.
- Surfaces: Punched or machined surfaces 125 micro inches rms max.
- Break all sharp edges .015' R max.
- Manufacturer to add UL Vendor ID Number , Date Code (YY/WW Format) in this area on the bottom side side silkscreen.



Critical Dimension: 0.1mm thickness between L2 and L3